

**AMENDMENTS TO THE SPECIFICATION**

Please replace the following sections of the Specification. Applicant includes herewith a marked up version of the replacement paragraphs, underlined and/or bracketed text indicating insertions, and strikethrough and/or double brackets indicating deletions.

*Please replace paragraph [0015] of the Specification with the following:*

[0015] A protective cap 40 is attached to the back side 14 of the semiconductor chip 10. The protective cap 40 includes a first surface 42 facing the semiconductor chip 10 and a second surface 44 opposite of the first surface 42 and exposed to the outside of the flip package. Also, the protective cap 40 includes an extended portion 40a extending beyond the periphery of the semiconductor chip 10. A dovetail groove 46, opening toward the first surface 42, is formed in the extended portion 40a. In FIG. 1, the dovetail groove 46 is represented as an opening having a depth equal to the entire thickness of the protective cap 40, but it may be formed as a blind hole having a depth less than the thickness of the protective cap 40 as illustrated in FIG. 5. The protective cap 40 includes metal to protect the semiconductor chip 10 from shocks. For example, the protective cap 40 may be made of copper (Cu), copper alloy, aluminum (Al), or aluminum alloy. The protective cap 40 is capable of maintaining the excellent heat-conductive property of the flip chip package.

*Please insert the following paragraph after paragraph [0013] of the Specification:*

FIG. 5 illustrates a cross-sectional view of a flip chip package with a dovetail groove having a thickness less than a thickness of a protective cap according to another example embodiment of the present invention.